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□□ □□ : BEST-507 250G □□ □□□□

00 : 000 / 000 / 000 / 00 00 SMD IC 0 BGA IC 00, 0 00 000000 00 00 00 00...0

SOLDER PASTE

low temperature



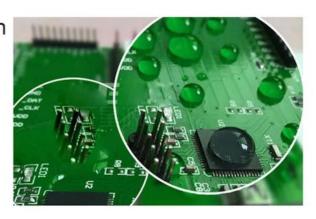
500g Low residue / Rapid welding / Solder spot bright

Product Usage

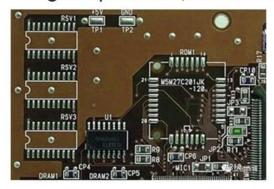


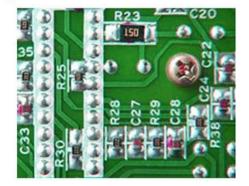
MODEL	BST-508
SHELF LIFE	6 months
INGREDIENT	Sn63/Pb37
WEIGHT	500g
MELTING POINT	183 ℃

Having a large insulation resistance does not corrode the PCB, and the requirements for no-cleaning can be achieved.



High impedance, full and bright solder, low residue





Welding requirements for a wide range of products





UNIFORM SOLDER JOINT LOW TEMPERATURE MELTING POINT



PRODUCT SIZE





63.0MM 52MM

